This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1(previously presented). A method of providing a desired range of point-to-ground resistance to trays, comprising:

coating a conductive solution onto a polymer film to obtain a conductive sheet having an antistatic layer thereon;

forming a tray having cut surfaces with the conductive sheet; and

forming a conductive pathway on all or parts of the cut surfaces of the tray.

2(previously presented). The method according to claim 1, wherein the conductive pathway is formed by coating a conductive solution to the cut surfaces of the tray having insulative properties.

3(original). The method according to claim 2, wherein the coating of the conductive solution is performed by a heat curing process or a UV-curing process.

4(previously presented). The method according to claim 2, wherein the conductive solution comprises 0.05-40 wt% of a conductive material, the conductive material being selected from the group consisting of a conductive polymer, conductive carbon, a metal, metal oxide, a surfactant, and mixtures thereof.

5(original). The method according to claim 4, wherein the conductive polymer is selected from the group consisting of polypyrrole, polyaniline, polythiophene, derivatives thereof, and mixtures thereof.

6(original). The method according to claim 5, wherein the derivative of the conductive polymer is selected from the group consisting of polythiophene having C_5-C_{12} alkyl, 3,4-ethylenedioxy-substituted polythiophene, polyaniline having C_1-C_4 alkoxy, amino or sulfone, polypyrrole having C_5-C_{12} alkyl, and mixtures thereof.

7(original). The method according to claim 4, wherein the conductive carbon comprises conductive carbon black, carbon fiber, or carbon nanotube.

8(original). The method according to claim 4, wherein the metal comprises silver or copper.

9(original). The method according to claim 4, wherein the metal oxide comprises doped indium oxide or tin oxide.

10(original). The method according to claim 4, wherein the surfactant comprises quaternary ammonium salts, ionic surfactants, non-ionic surfactants, or amine surfactants.

11(previously presented). The method according to claim 2, wherein the conductive solution is coated at a thickness of 0.05-5 μm to the cut surfaces of the tray.

12(original). The method according to claim 1, wherein the conductive pathway is formed by using an antistatic polymer or a metal clamp or a metal clip.

13(original). The method according to claim 1, wherein the conductive pathway is formed by attaching an antistatic and conductive tape to the cut surfaces of the tray.

Claims 14-15(canceled).

16(previously presented). The method according to claim 3, wherein the conductive solution comprises 0.05-40 wt% of a conductive material, the conductive material being selected from the group consisting of a conductive polymer, conductive carbon, a metal, metal oxide, a surfactant, and mixtures thereof.

17(previously presented). The method according to claim 16, wherein the conductive polymer is selected from the group consisting of polypyrrole, polyaniline, polythiophene, derivatives thereof, and mixtures thereof.

18(previously presented). The method according to claim 17, wherein the derivative of the conductive polymer is selected from the group consisting of polythiophene having C_5-C_{12} alkyl, 3,4- ethylenedioxy-substituted polythiophene, polyaniline having C_1-C_4 alkoxy, amino or sulfone, polypyrrole having C_5-C_{12} alkyl, and mixtures thereof.

19(previously presented). The method according to claim 16, wherein the metal oxide comprises doped indium oxide or tin oxide.

20(previously presented). The method according to claim 16, wherein the surfactant comprises quaternary ammonium salts, ionic surfactants, non-ionic surfactants, or amine surfactants.

21(cancelled).